Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	85424	((microelectronic\$1) or (micro-electronic\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:21
L2	21711	((microelectronic\$1) or (micro-electronic\$1)) near3 (element\$1 or component\$1 or device\$1 or chip\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:21
L3	4308861	(etch\$3 or remov\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:22
L4	14872	2 and 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:22
L5	179115	"438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:22
L6	3576	4 and 5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:22
L7	1097	6 and (etch\$3 or remov43) same (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:23
L8	1541	6 and (etch\$3 or remov\$3) same (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/03/27 11:50
L9	176	7 and (solder\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:24

L10	16	6 and (etch\$3 or remov\$3) with (protru\$5) same (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/03/27 11:56
L11	80	6 and (etch\$3 or remov\$3) with (protru\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:56
L12	60	6 and (remov\$3) with (protru\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/03/27 11:57

`L10	16	6 and (etch\$3 or remov\$3) with (protru\$5) same (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:56	
L11	. 80	6 and (etch\$3 or remov\$3) with (protru\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/03/27 11:56	
L12	60	6 and (remov\$3) with (protru\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 12:09	
L13	4558773	(remov\$3) neaar5 (protru\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 12:10	
L14	105192	5 and 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 12:09	
L15	11140	(remov\$3) near5 (protru\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:58	
L16	780	5 and 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:53	
L17	64	16 and (micro-electronic\$1 or microelectronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:58	
L18	305393	(remov\$3) near5 (layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:58	
L19	57515	5 and 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:58	

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L20	6071	19 and (micro-electronic\$1 or microelectronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:59
L21	114	20 and (remov\$3) with (protru\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:05
L22	6071	20 and (remov\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:47
L23	6071	5 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:06
L24	307	23 and (assembl\$3) with (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:47
L25	417	20 and (mold\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/03/27 16:56
L26	5705	20 and (etch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:47
L27	263	26 and (assembl\$3) with (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:55
L28	3901	(assembl\$3) with (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:55
L29	868	28 and (mold\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:56

L30	296	29 and (bump\$1 or silder\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:57
L31	562	29 and (bump\$1 or solder\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:57

Ref	Hits	Search Query	DBs	Default	Plurals	Time Stamp
# L1	85424	((microelectronic\$1) or	US-PGPUB;	Operator OR	ON	2006/03/27 11:21
	05724	(micro-electronic\$1))	USPAT; EPO; JPO; DERWENT; IBM_TDB	OK .	ON	2006/03/27 11:21
L2	21711	((microelectronic\$1) or (micro-electronic\$1)) near3 (element\$1 or component\$1 or device\$1 or chip\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:21
L3	4308861	(etch\$3 or remov\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	.OR	ON	2006/03/27 11:22
L4	14872	2 and 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:22
L5	179115	"438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:22
L6	3576	4 and 5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:22
L7	1097	6 and (etch\$3 or remov43) same (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:23
L8	1541	6 and (etch\$3 or remov\$3) same (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:50
L9	176	7 and (solder\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:24

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L10	16	6 and (etch\$3 or remov\$3) with (protru\$5) same (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:56
L11	. 80	6 and (etch\$3 or remov\$3) with (protru\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:56
L12	60	6 and (remov\$3) with (protru\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 12:09
L13	4558773	(remov\$3) neaar5 (protru\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 12:10
L14	105192	5 and 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 12:09
L15	11140	(remov\$3) near5 (protru\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:58
L16	780	5 and 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:53
L17	64	16 and (micro-electronic\$1 or microelectronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:58
L18	305393	(remov\$3) near5 (layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:58
L19	57515	5 and 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:58

L20	6071	19 and (micro-electronic\$1 or microelectronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 15:59
L21	114	20 and (remov\$3) with (protru\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:05
L22	6071	20 and (remov\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:47
L23	6071	5 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON -	2006/03/27 16:06
L24	307	23 and (assembl\$3) with (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:47
L25	417	20 and (mold\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:56
L26	5705	20 and (etch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:47
L27	263	26 and (assembl\$3) with (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:55
L28	3901	(assembl\$3) with (microelectronic\$1 or micro-electronic\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:55
L29	868	28 and (mold\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:56

L30	296	29 and (bump\$1 or silder\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 16:57
L31	562	29 and (bump\$1 or solder\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 17:22
L32	2	"6280664".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 17:23
L33	2	"6280644".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 17:23
L34	118649	(remov\$3) near10 (insulat\$3 or dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 17:24
L35	460	28 and 34	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 17:24
L36	163	5 and 35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 17:24